WHAT IS CLAIMED IS:

1. A lithography system including an exposure apparatus which exposes a substrate to project a pattern onto it on which resist is coated, and a substrate processing apparatus connected to said exposure apparatus and adapted to process the substrate, the system comprising:

an environment sensor which measures an environment of at least one of the said exposure apparatus and said substrate processing apparatus; and

a control device which controls the environment of at least one of said exposure apparatus and said substrate processing apparatus on the basis of a measured value given from said environment sensor in such a manner that the environment in said exposure apparatus becomes substantially the same as the environment in said substrate processing apparatus.

2. A lithography system according to claim 1, wherein said environment sensor measures at least one of pressure, temperature and humidity in said apparatus.

3. A lithography system according to claim 2, wherein said substrate processing apparatus has at least one of a resist coating function and a developing function.

4. A lithography system according to claim 1 ~~or 3~~, wherein the resist coated on the substrate is chemically amplified resist.

5. A lithography method for controlling an environment in an exposure apparatus which is adapted to expose a substrate and which is connected to a substrate processing

apparatus which processes the substrate before or after exposure, the method comprising the steps of:

obtaining data regarding the environment in said substrate processing apparatus; and

controlling the environment in said exposure apparatus on the basis of the obtained data.

6. A method according to claim 5, wherein said substrate processing apparatus includes at least one of a coater which coats sensitive agent on the substrate before the exposure and a developer which develops the substrate after the exposure.

7. A method according to claim 5, wherein the environment in said exposure apparatus is controlled to be substantially the same as the environment in said substrate processing apparatus.

8. A method according to claim 5, wherein the data relates to at least one of air pressure, temperature and humidity.

9. A method according to claim 5, wherein said exposure apparatus and said substrate processing apparatus are housed in independent chambers.

10. A method according to claim 5, wherein said exposure apparatus and said substrate processing apparatus are assembled as an in-line system.

11. A method according to claim 5, wherein chemically amplified resist is coated on the substrate.

12. A lithography method for controlling an environment in a substrate processing apparatus which is adapted to

process a substrate before or after exposure and which is connected to an exposure apparatus which exposes the substrate before or after the processing, the method comprising the steps of:

obtaining data regarding the environment in said exposure apparatus; and

controlling the environment in said processing apparatus on the basis of the obtained data.

13. A processing apparatus according to claim 12, wherein it includes at least one of a coater which coats sensitive agent on the substrate before the exposure and a developer which develops the substrate after the exposure.

14. A processing apparatus according to claim 12, wherein the environment in said substrate processing apparatus is controlled to be substantially the same as the environment in said exposure apparatus.

15. A processing apparatus according to claim 12, wherein the data relates to at least one of air pressure, temperature and humidity.

16. A method according to claim 12, wherein said exposure apparatus and said substrate processing apparatus are housed in independent chambers.

17. A method according to claim 12, wherein the data relates to at least one of air pressure, temperature and humidity.

18. A method according to claim 12, wherein said exposure apparatus and said processing apparatus are housed in independent chambers.

19. A method according to claim 12, wherein said exposure apparatus and said processing apparatus are assembled as an in-line system.

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20. A method for making an exposure apparatus which is adapted to expose a substrate and which is connected to a processing apparatus which processes the substrate before or after exposure, the method comprising the steps of:

providing an adjusting device which adjusts an environment in said exposure apparatus; and

providing a control device which controls said adjusting device on the basis of data regarding the environment in said substrate processing apparatus.

21. A method according to claim 20, wherein said substrate processing apparatus includes at least one of a coater which coats sensitive agent on the substrate before the exposure and a developer which develops the substrate after the exposure.

22. A method according to claim 20, wherein the data relates to at least one of air pressure, temperature and humidity.

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23. A method for making a substrate processing apparatus which is adapted to process a substrate and which is connected to an exposure apparatus which exposes the substrate before or after the processing, the method comprising the steps of:

providing an adjusting device which adjusts an environment in said substrate processing apparatus; and

providing a control device which controls said

adjusting device on the basis of data regarding the environment in said exposure apparatus.

24. A method according to claim 23, wherein said substrate processing apparatus includes at least one of a coater which coats sensitive agent on the substrate before the exposure and a developer which develops the substrate after the exposure.

25. A method according to claim 23, wherein the data relates to at least one of air pressure, temperature and humidity.

26. A lithography method using an exposure apparatus which exposes a substrate and a substrate processing apparatus which processes the substrate before or after exposure, the method comprising the steps of:

obtaining data regarding an environment in one of said exposure apparatus and said substrate processing apparatus; and

controlling the environment in the other apparatus on the basis of the obtained data.

27. An exposure apparatus adapted to expose a substrate and connected to a substrate processing apparatus which processes the substrate before or after exposure, the exposure apparatus comprising:

a chamber disposed around an exposure body system which exposes the substrate;

an adjusting device connected to said chamber and adapted to adjust an environment in said chamber; and

a control device connected to said adjusting device

and adapted to control said adjusting device on the basis of data regarding the environment in said substrate processing apparatus.

28. A substrate processing apparatus adapted to process a substrate and connected to an exposure apparatus which exposes the substrate before or after the substrate processing, the substrate processing apparatus comprising:

a chamber disposed around a substrate processing body system which processes the substrate;

an adjusting device connected to said chamber and adapted to adjust an environment in said chamber; and

a control device connected to said adjusting device and adapted to control said adjusting device on the basis of data regarding environment in said exposure apparatus.